


MATERIAL DECLARATION SHEET



Material Number	CDSOT563-T05C			
Product Line	Semiconductor Products			
Compliance Date	2008/7/29			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\	CASRN	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Die Chip	Wafer	0.085	Silicon	7440-21-3	99.00	0.084	2.23
				other	-	1.00	0.001	
2	Leadframe	CAC92	1.098	Manganese	7439-96-5	0.30	0.003	28.84
				Nickel	7440-02-0	9.50	0.104	
				Iron	7439-89-6	0.60	0.007	
				Tin	7440-31-5	2.30	0.025	
				Zinc	7440-66-6	0.50	0.005	
				Lead	7439-92-1	0.05	0.001	
				Copper	7440-50-8	86.74	0.952	
				Silver	7440-22-4	0.01	0	
3	Epoxy	Epoxy	0.32	Silver	7440-22-4	74.50	0.238	8.41
				Epoxy resin	TS ref# 10030	15.00	0.048	

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				1,4-Butanedioldiglycidyl ether	2425-79-8	7.50	0.024	
				Amine	TS ref# 10039	3.00	0.01	
4	Wire	Au	0.076	Aurum	7440-57-5	100.00	0.076	1.99
5	Compound	Outer	2.171	Silica	60676-86-0	80.00	1.737	57.03
				Epoxy Resin	Trade Secret	10.00	0.217	
				Phenolic Resin	Trade Secret	9.70	0.211	
				Carbon Black	1333-86-4	0.30	0.007	
6	Plating	Sn	0.057	Tin	7440-31-5	100.00	0.057	1.5
		Total weight	3.807					

This Document was updated on: 2015/12/14

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. * 7(a)-Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead)